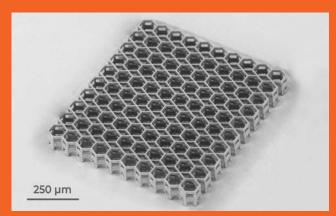
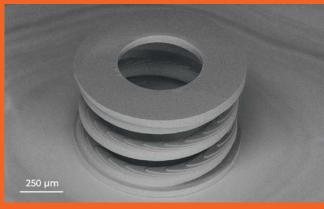


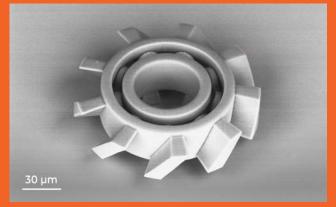
3D Structures on Fiber Tip



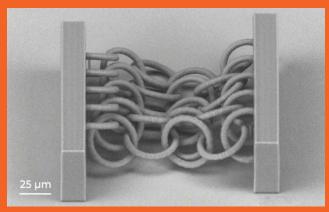
3D Scaffold



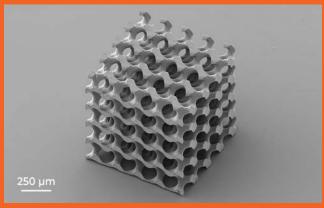
3D Meso-Spring



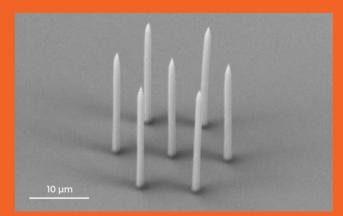
3D Scaffold



**3D Chain-Mail Structure** 



3D Gyroid Structure



Microneedles



3D Gyroid Structure

# MULTIPHOTON POLYMERIZATION



## **APPLICATIONS**

- Micro-optics
- Micro-mechanics
- Scaffolds
- Sensors
- Interconnects

#### **FEATURES**

- Nanometer resolution additive manufacturing technique
- True 3D structures in micrometer scale
- Various polymers available
- Stitching error-free manufacturing

**Multiphoton-polymerization** (MPP) is a technology that enables the production of arbitrary shape polymeric structures within submicrometric resolution. First, a photoresist sample is prepared by drop-casting polymer material mixed with a photoinitiator on the glass slide and then pre-baking. Afterward, the 3D microstructure is fabricated using a direct laser writing technique. Consequently, the polymer hardens in places of drop where it is affected by laser radiation due to a process called photopolymerization. Finally, the microstructure is immersed in an organic solvent to develop an unpolymerized photoresist.

MPP is often used in the manufacturing of microelectronic devices, as it allows for the creation of very small and detailed structures with high levels of precision. Additionally, because the light is highly focused, it can be used to create complex 3D shapes.

# SPECIFICATIONS

	·
Technology	Additive manufacturing
Materials	SZ2080, SU-8, Ormocers, Glassomer, hybrid organic-inorganic photopolymers, elastomers, proteins
Minimum XY feature size	150 nm
Minimum surface roughness Ra	≤ 20 nm
Maximum fabrication speed	30 mm/s

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## **TECHNICAL SPECIFICATIONS**

Technology	Multiphoton Polymerization	Selective Laser Etching	Hybrid
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#### LASER SOURCE

	Wavelength	780 nm	1030 ± 10 nm 515 ± 10 nm		1030 ± 10 nm	1030 ± 10 nm and 515 ± 10 nm
	Repetition rate	100 MHz	11 MHz 76 MHz	Single-shot – 1 MHz	Single-shot – 1 MHz	Single-shot – 1 MHz
Femtosecond laser	Pulse duration	< 100 fs	50 fs 120 fs 170 fs	290 fs – 20 ps (tunable)	250 fs (450 fs) – 10 ps (tunable)	190 fs – 10 ps (tunable)
	Max. average power	250 mW	2 W	5 W	10 W	from 5 W to 20 W*
	Long-term power stability	< 0.5% RMS over 24 h	< 0.5% RMS over 100 h			

#### POSITIONING

XYZ POSITIONING	S STAGES MOUNTED ON GRANITE BASE WITH BRIDGE
Travel (XYZ)	160 mm × 160 mm × 60 mm *
Accuracy (XYZ)	± 300 nm
Resolution (XYZ)	lnm
Maximum speed (XY)	200 mm/s
GALVANO SCANNERS	
Accuracy	50 µrad
Repeatability	0.4 µrad RMS
	Travel (XYZ) Accuracy (XYZ) Resolution (XYZ) Maximum speed (XY) GALVANO SCANN Accuracy

#### **OTHER PARAMETERS**

Monitoring on time	The fabrication process is monitored by an integrated machine vision system		
Stitching	Stitchless fabrication using Infinite Field of View (IFoV)		
Focusing optics	Objectives – from 0.4 to 1.4 NA *	Objectives – from 0.25 to 0.45 NA *	Objectives – from 0.25 to 1.4 NA *
Autofocus system	Automatic glass/polymer or glass/air interface optical detection		
Self-Align-System (SAS)	Automatic laser beam path alignment system		
Substrate	Universal vacuum sample holder with computer-controlled, position synchronized illumination for transparent samples		



Technology	Multiphoton Polymerization	Selective Laser Etching	Hybrid
Beam delivery & control	Motorized attenuator, polarization rotat power meter enables real-time power n		Integrated
Software	Convenient control of all necessary prod settings. The software handles standard by popular CAD programs, like STL	•	
Laser safety	5	Ergonomic housing to ensure laser safety class 1 and environment stability conditions for laser microfabrication process	

\* Customizable.

# PHYSICAL DIMENSIONS

Dimensions when all doors are closed (W $\times$ L $\times$ H)	1790 mm × 920 mm × 2270 mm
Dimensions when doors are opened (W $\times$ L $\times$ H)	2680 mm × 1900 mm × 2300 mm
Weight	~ 700 kg

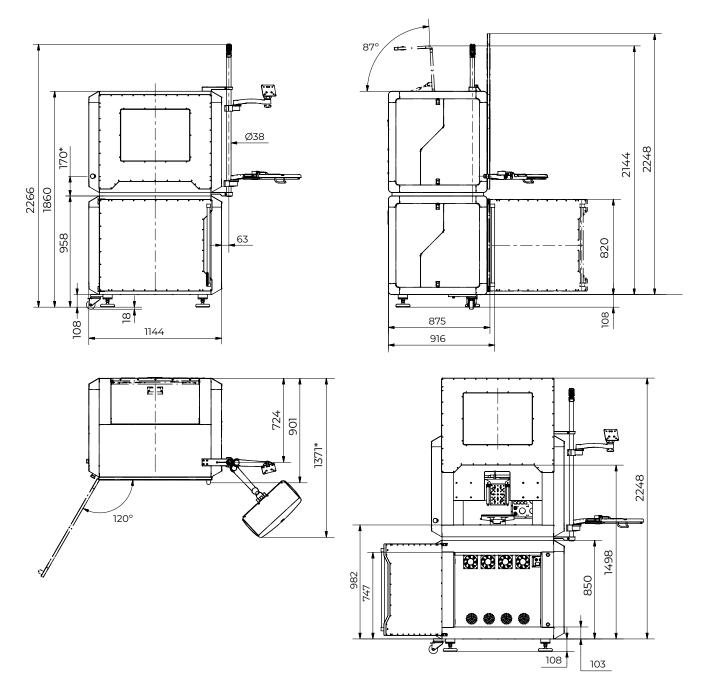
# ENVIRONMENTAL & UTILITY REQUIREMENTS

Operating temperature	20 °C ± 2 °C
Relative humidity	≤ 60%
Electrical requirements	110 V AC, 20 A – 230 V AC , 10 A
AC power (normal operation)	typical 2 kW

The conditions of the environment are preferred to be as stable as possible.



## DRAWINGS







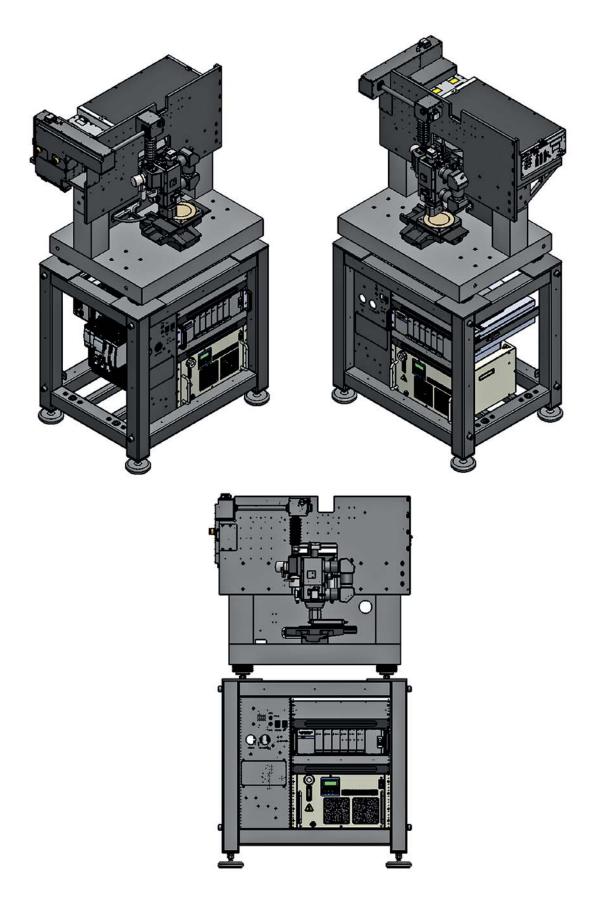


Figure 2. Laser Nanofactory drawings

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